



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Yuko UCHIMARU, et al.

SERIAL NO: 10/809,704

GAU:

FILED: March 26, 2004

EXAMINER:

FOR: LOW DIELECTRIC CONSTANT INSULATING MATERIAL AND SEMICONDUCTOR DEVICE USING THE MATERIAL

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. In accordance with discussions on August 4, 2004 with Mr. Nicholas P. Godici, Commissioner for Patents, it is no longer required to submit copies of cited pending applications. A modification of the Rules will be published soon in the Official Gazette. Cited issued patents, if any, are listed on the attached PTO form 1449.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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MAIER & NEUSTADT, P.C.
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STATEMENT OF RELEVANCY

All of the references on Form PTO-1449 are discussed in the specification.

NOV 15 2004

SHEET 1 OF 1

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 251148US0	TRADEMARK OFFICE		SERIAL NO. 10/809,704
LIST OF REFERENCES CITED BY APPLICANT		APPLICANT Yuko UCHIMARU, et al.					
		FILING DATE March 26, 2004				GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
					YES	NO	
	AO	2002-317049	10/31/2002	JAPAN (with English Abstract)			X
	AP	2968244	08/20/1999	JAPAN (with English Abstract)			X
	AQ	3041424	03/10/2000	JAPAN (with translation of claim 1)			X
	AR	2002-359240	12/13/2002	JAPAN (with English Abstract)			X
	AS	2003-119289	04/23/2003	JAPAN (with English Abstract)			X
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AW	International Technology Roadmap for Semiconductors 2002 Update, 2002 Update Tables, page 75, "TABLE 62A MPU INTERCONNECT TECHNOLOGY REQUIREMENTS—NEAR-TERM", 2002					
	AX	S. SHINMIYAHARA, et al., Cu-Interconnect Technology, page 227, "LATEST DEVELOPMENT OF CU WIRING TECHNIQUES", (with partial English translation)					
	AY						
	AZ					<input type="checkbox"/> Additional References sheet(s) attached	
Examiner				Date Considered			
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							